

Test Ordyl Wafer + Membrane | K0320

2020-09

1 Masks

Single mask for **Ordyl**

2 Short description of the fabrication process:

4x pyrex wafer with ordyl 4x SiOx wafers with Neopolim S100

3 Process

1. Std Clean III. On all 4x Pyrex wafers
2. HMDS-priming oven. Std recipe
3. Laminate 1x55 μm sheet of Ordyl SY355
4. Expose: "Ordyl" darkfield mask @ (27 s | 9 mW)
5. Post Exposure Bake: 85 °C, 3 min (take off plastic laminate before bake)
6. Ordyl development in BMR developer Develop until structures are well defined, iso to remove developer, rinse. Use 10% US power about 10 mins
7. Hardbake: 110 °C, 60 - 120 mins

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8. Dicing. Fragile, use blue tape by hand and no vacuum.
 9. Substrate thickness 4x500 μm (borosilicate) Feed speed: 3 mm/s

10. Cut distance: 33.2 mm x 33.2 mm (chip size: 33 mm x 33 mm)

11. □ 4x Si wafers

12. 2.5 ml Dispense Neopolim S100 (18%wt)

13. Spin coating: 15s 500RPM ; 15s 800RPM ; 30s 3000RPM

14. Initial bake: 120°C 2 min

15. Ramp: 200°C

16. Final bake: 200°C 60 min

4 Notes